

ABSTRACT OF THE DISCLOSURE

An exposure apparatus according to this invention includes a projection optical system having a
5 predetermined image forming characteristic; a reticle stage, arranged on one side of the projection optical system, and which holds a reticle having a transfer pattern and has a reference plate for positioning; and a
10 wafer stage, arranged on the other side of the projection optical system, and which holds a wafer where the transfer pattern is transferred and has a reference mark. For transferring the transfer pattern to the wafer, a reticle protection pellicle and an optical device are arranged between the reticle and the projection optical system.
15 For performing positioning using the reference plate and the reference mark, a correction optical device is arranged between the reference plate and the projection optical system. The correction optical device has a thickness equal to the total thickness of the optical
20 device and pellicle.

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